

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	893	die near bump\$4 and solder and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:33
L2	36	1 and microwave	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:35
L3	4	2 and microwave near (solder\$4 or heat\$4 or reflow)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:36
L6	44	microwave near (solder\$4 or reflow) and solder\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/03 14:36